

## Test Run Details





Show details of selected Test Run associated with registered component of the Inner Tracker.

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ModuleQC::PixelFailureTest




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Basic Properties

INSTITUTE	RUN NUMBER	✓
 Tokyo Institute of Technology TITECH	...	
TEST DATE	TEST TYPE	
13.11.2020 19:31	  ModuleQC::PixelFailureTest PIXEL_FAILURE_TEST	
UPLOADED		
 Hiroki Okuyama		


Associated Components










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  Front-end Chip - RD53A 20UPGFC9999999 

Tested at stage: 

Test after bump bonding on module

Properties	
QC stage	MODULEWIREBONDING 

Results		
Noisy	0	
High ENC	452	
Tuning Bad ToT	0	
Tuning Bad Threshold	2105	
Tuning Failed	255	
Analog Bad	12350	
Analog Dead	11792	
Digital Bad	0	
Digital Dead	0	

Defects

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Attachments

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std_digitalscan_datafiles.zip	▼
std_digitalscan_configfiles.zip	▼
std_analogscan_datafiles.zip	▼
std_analogscan_configfiles.zip	▼
std_thresholdscan_datafiles.zip	▼
std_thresholdscan_configfiles.zip	▼
std_totscan_datafiles.zip	▼
std_totscan_configfiles.zip	▼
std_noisescan_datafiles.zip	▼
std_noisescan_configfiles.zip	▼

Comments

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